

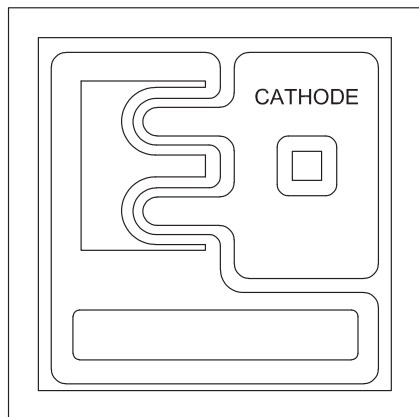
**PROCESS CPZ40X**  
**Transient Voltage Suppressor**  
5 Volt TVS Chip



**PROCESS DETAILS**

Die Size	13.4 x 13.4 MILS
Die Thickness	5.5 MILS
Cathode Bonding Pad Area	3.9 x 6.7 MILS
Top Side Metalization	Al - 30,000Å
Back Side Metalization	Au - 9,000Å

**GEOMETRY**



BACKSIDE ANODE R0

**GROSS DIE PER 5 INCH WAFER**

122,493

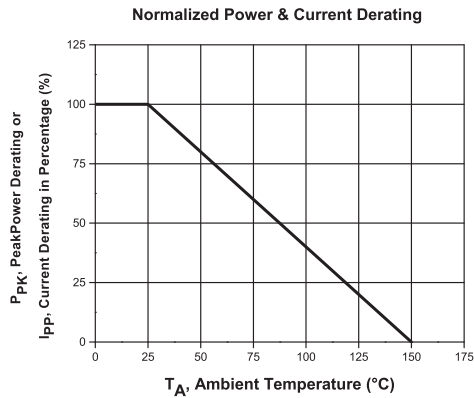
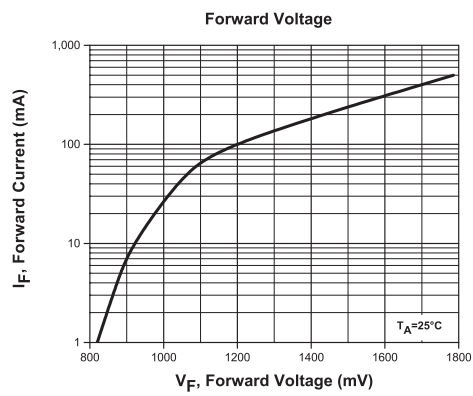
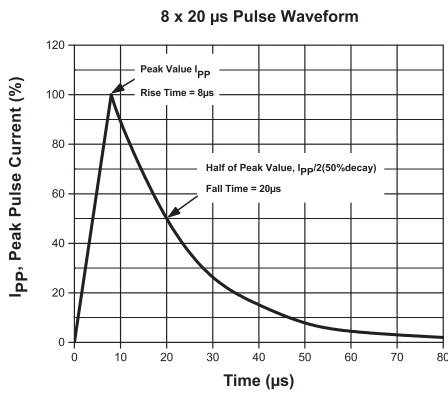
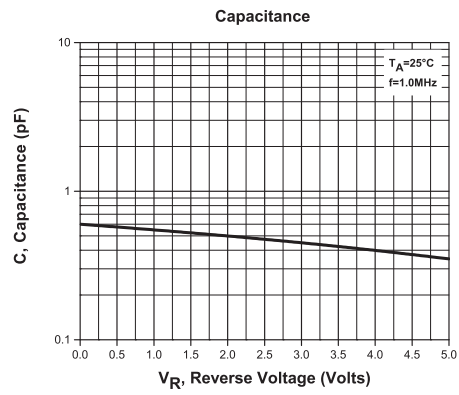
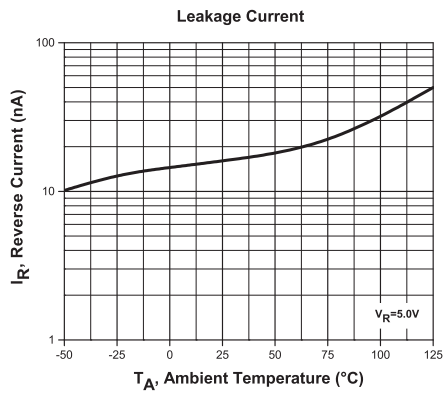
**PRINCIPAL DEVICE TYPE**

CMO5V0LC

R0 (9-January 2013)

# PROCESS CPZ40X

## Typical Electrical Characteristics



R0 (9-January 2013)